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Provisional Data Sheet No. PD-9.552B

急出货

International
IR Rectifier

HEXFET® POWER MOSFET

JANTX2N6845

JANTXV2N6845

[REF:MIL-PRF-19500/563]

[GENERIC:IRFF9120]

P-CHANNEL

-100 Volt, 0.60Ω HEXFET

HEXFET technology is the key to International Rectifier's advanced line of power MOSFET transistors. The efficient geometry achieves very low on-state resistance combined with high transconductance.

HEXFET transistors also feature all of the well-established advantages of MOSFETs, such as voltage control, very fast switching, ease of paralleling and electrical parameter temperature stability. They are well-suited for applications such as switching power supplies, motor controls, inverters, choppers, audio amplifiers, and high energy pulse circuits, and virtually any application where high reliability is required.

Product Summary

| Part Number | BVDSS | RDS(on) | ID |
|--------------|-------|---------|-------|
| JANTX2N6845 | -100V | 0.60Ω | -4.0A |
| JANTXV2N6845 | | | |

Features:

- Avalanche Energy Rating
- Dynamic dv/dt Rating
- Simple Drive Requirements
- Ease of Parallelizing
- Hermetically Sealed

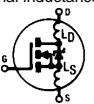
Absolute Maximum Ratings

| | Parameter | JANTX2N6845, JANTXV2N6845 | Units |
|-----------------------------|-----------------------------|--|-------|
| ID @ VGS = -10V, TC = 25°C | Continuous Drain Current | -4.0 | A |
| ID @ VGS = -10V, TC = 100°C | Continuous Drain Current | -2.6 | |
| IMD | Pulsed Drain Current ① | -16 | |
| PD @ TC = 25°C | Max. Power Dissipation | 20 | W |
| | Linear Derating Factor | 0.16 | W/K ⑤ |
| VGS | Gate-to-Source Voltage | ±20 | V |
| dv/dt | Peak Diode Recovery dv/dt ③ | -5.0 | V/ns |
| TJ | Operating Junction | -55 to 150 | °C |
| TSTG | Storage Temperature Range | | |
| | Lead Temperature | 300 (0.063 in. (1.6mm) from case for 10.5 seconds) | |
| | Weight | 0.98 (typical) | g |

JANTX2N6845, JANTXV2N6845 Device

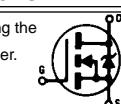
Electrical Characteristics @ $T_j = 25^\circ\text{C}$ (Unless Otherwise Specified)

| | Parameter | Min. | Typ. | Max. | Units | Test Conditions |
|--|--|------|-------|------|---------------------------|--|
| BV_{DSS} | Drain-to-Source Breakdown Voltage | -100 | — | — | V | $\text{V}_{\text{GS}} = 0\text{V}$, $\text{I}_D = -1.0\text{ mA}$ |
| $\Delta \text{BV}_{\text{DSS}}/\Delta T_j$ | Temperature Coefficient of Breakdown Voltage | — | -0.10 | — | $\text{V}/^\circ\text{C}$ | Reference to 25°C , $\text{I}_D = -1.0\text{ mA}$ |
| $\text{R}_{\text{DS}(\text{on})}$ | Static Drain-to-Source On-State Resistance | — | — | 0.60 | Ω | $\text{V}_{\text{GS}} = -10\text{V}$, $\text{I}_D = -2.6\text{A}$ ^④ |
| | | — | — | 0.69 | | $\text{V}_{\text{GS}} = -10\text{V}$, $\text{I}_D = -4.0\text{A}$ |
| $\text{V}_{\text{GS}(\text{th})}$ | Gate Threshold Voltage | -2.0 | — | -4.0 | V | $\text{V}_{\text{DS}} = \text{V}_{\text{GS}}$, $\text{I}_D = -250\mu\text{A}$ |
| g_{fs} | Forward Transconductance | 1.25 | — | — | $\text{S} (\text{t})$ | $\text{V}_{\text{DS}} > -15\text{V}$, $\text{I}_{\text{DS}} = -2.6\text{A}$ ^④ |
| IDSS | Zero Gate Voltage Drain Current | — | — | -25 | μA | $\text{V}_{\text{DS}} = 0.8 \times \text{Max Rating}$, $\text{V}_{\text{GS}} = 0\text{V}$ |
| | | — | — | -250 | | $\text{V}_{\text{DS}} = 0.8 \times \text{Max Rating}$ $\text{V}_{\text{GS}} = 0\text{V}$, $T_j = 125^\circ\text{C}$ |
| IG_{SS} | Gate-to-Source Leakage Forward | — | — | -100 | nA | $\text{V}_{\text{GS}} = -20\text{V}$ |
| IG_{SS} | Gate-to-Source Leakage Reverse | — | — | 100 | | $\text{V}_{\text{GS}} = 20\text{V}$ |
| Q_{g} | Total Gate Charge | 4.3 | — | 16.3 | nC | $\text{V}_{\text{GS}} = -10\text{V}$, $\text{I}_D = -4.0\text{A}$ |
| Q_{gs} | Gate-to-Source Charge | 1.3 | — | 4.7 | | $\text{V}_{\text{DS}} = \text{Max. Rating} \times 0.5$ see figures 6 and 13 |
| Q_{gd} | Gate-to-Drain ("Miller") Charge | 1.0 | — | 9.0 | ns | $\text{V}_{\text{DD}} = -50\text{V}$, $\text{I}_D = -4.0\text{A}$, $\text{R}_G = 7.5\Omega$, $\text{V}_{\text{GS}} = -10\text{V}$ see figure 10 |
| $t_{\text{d}(\text{on})}$ | Turn-On Delay Time | — | — | 60 | | |
| t_{r} | Rise Time | — | — | 100 | | |
| $t_{\text{d}(\text{off})}$ | Turn-Off Delay Time | — | — | 50 | | |
| t_{f} | Fall Time | — | — | 70 | | |
| L_{D} | Internal Drain Inductance | — | 5.0 | — | nH | Measured from the drain lead, 6mm (0.25 in.) from package to center of die. |
| L_{S} | Internal Source Inductance | — | 15 | — | | Measured from the source lead, 6mm (0.25 in.) from package to source bonding pad. |
| C_{iss} | Input Capacitance | — | 380 | — | pF | $\text{V}_{\text{GS}} = 0\text{V}$, $\text{V}_{\text{DS}} = -25\text{V}$ |
| C_{oss} | Output Capacitance | — | 170 | — | | $f = 1.0\text{ MHz}$ |
| Cr_{ss} | Reverse Transfer Capacitance | — | 45 | — | | see figure 5 |



Source-Drain Diode Ratings and Characteristics

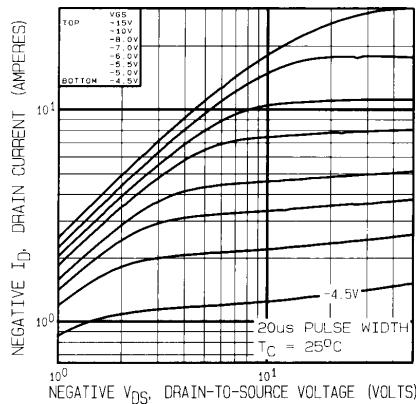
| | Parameter | Min. | Typ. | Max. | Units | Test Conditions |
|------------------------|--|--|------|------|---------------|---|
| I_{S} | Continuous Source Current (Body Diode) | — | — | -4.0 | A | Modified MOSFET symbol showing the integral reverse p-n junction rectifier. |
| I_{SM} | Pulse Source Current (Body Diode) ^① | — | — | -16 | | |
| V_{SD} | Diode Forward Voltage | — | — | -4.8 | V | $T_j = 25^\circ\text{C}$, $\text{I}_{\text{S}} = -4.0\text{A}$, $\text{V}_{\text{GS}} = 0\text{V}$ ^④ |
| t_{rr} | Reverse Recovery Time | — | — | 200 | ns | $T_j = 25^\circ\text{C}$, $\text{I}_{\text{F}} = -4.0\text{A}$, $d\text{I}/dt \leq -100\text{A}/\mu\text{s}$ |
| Q_{RR} | Reverse Recovery Charge | — | — | 3.1 | μC | $\text{V}_{\text{DD}} \leq -50\text{V}$ ^④ |
| t_{on} | Forward Turn-On Time | Intrinsic turn-on time is negligible. Turn-on speed is substantially controlled by $\text{L}_{\text{S}} + \text{L}_{\text{D}}$. | | | | |



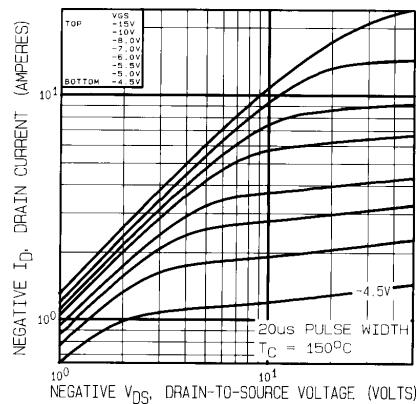
Thermal Resistance

| | Parameter | Min. | Typ. | Max. | Units | Test Conditions |
|--------------------------|---------------------|------|------|------|-------|----------------------|
| R_{thJC} | Junction-to-Case | — | — | 6.25 | K/W | Typical socket mount |
| R_{thJA} | Junction-to-Ambient | — | — | 175 | | |

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**Fig. 1 — Typical Output Characteristics
 $T_c = 25^\circ\text{C}$**



**Fig. 2 — Typical Output Characteristics
 $T_c = 150^\circ\text{C}$**

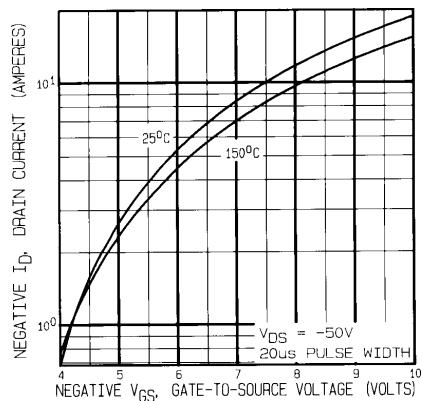


Fig. 3 — Typical Transfer Characteristics

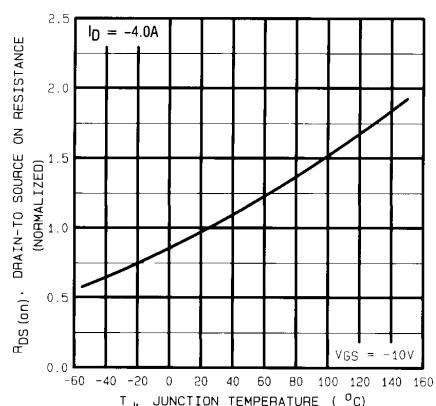


Fig. 4 — Normalized On-Resistance Vs. Temperature

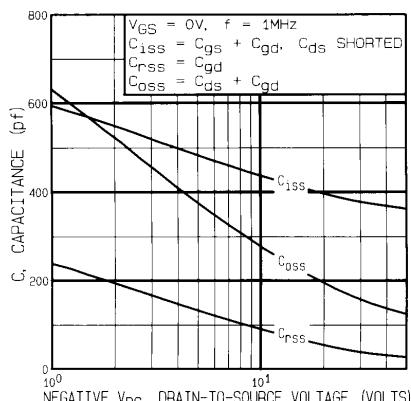


Fig. 5 — Typical Capacitance Vs. Drain-to-Source Voltage

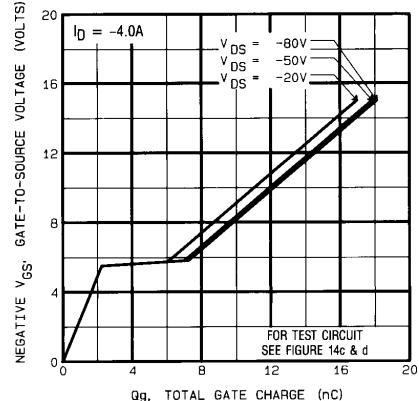


Fig. 6 — Typical Gate Charge Vs. Gate-to-Source Voltage

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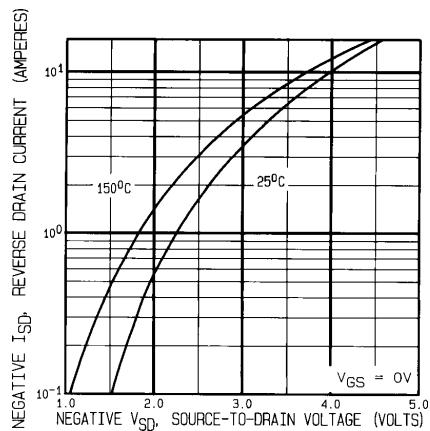


Fig. 7 — Typical Source-to-Drain Diode Forward Voltage

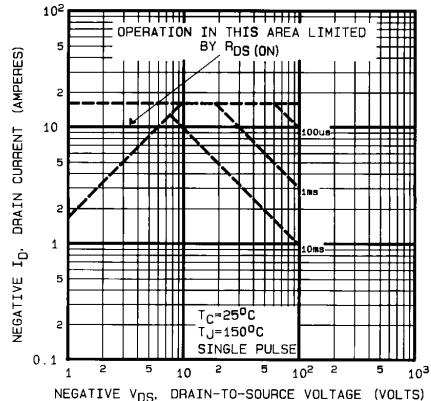


Fig. 8 — Maximum Safe Operating Area

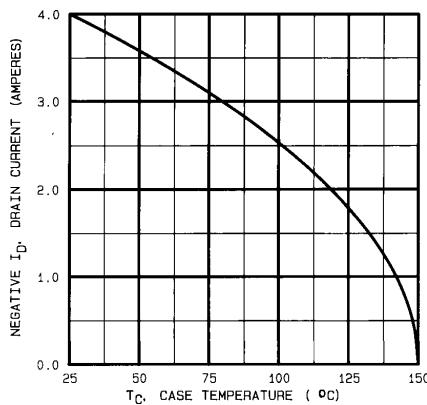


Fig. 9 — Maximum Drain Current Vs. Case Temperature

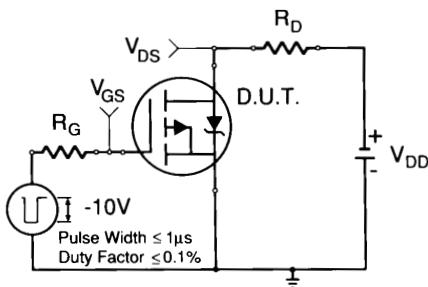


Fig. 10a — Switching Time Test Circuit

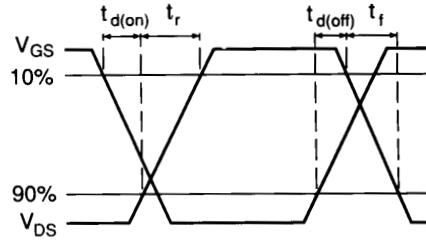


Fig. 10b — Switching Time Waveforms

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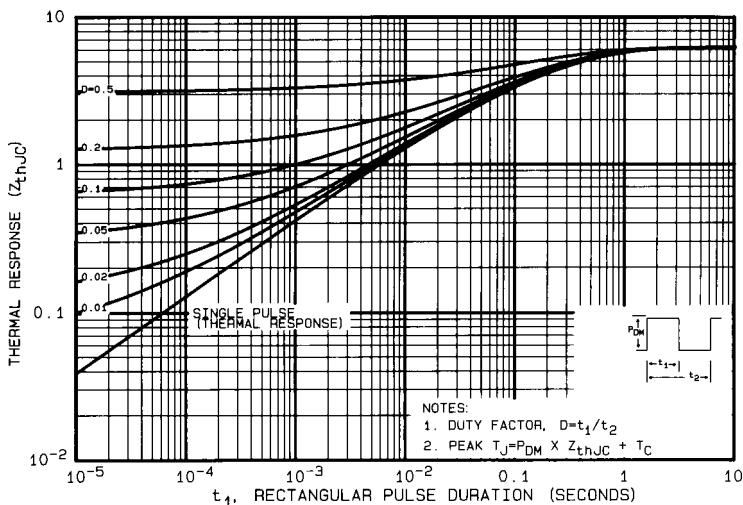


Fig. 11 — Maximum Effective Transient Thermal Impedance, Junction-to-Case Vs. Pulse Duration

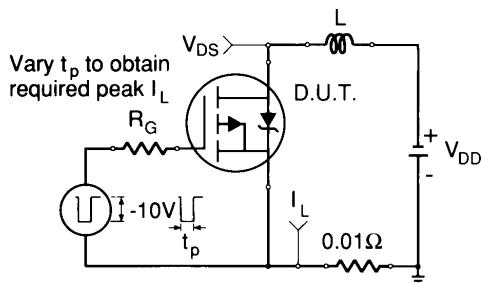


Fig. 12a — Unclamped Inductive Test Circuit

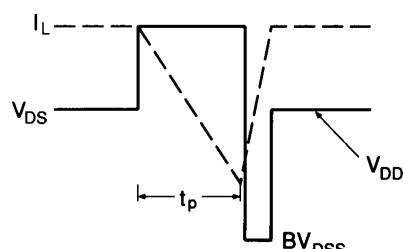


Fig. 12b — Unclamped Inductive Waveforms

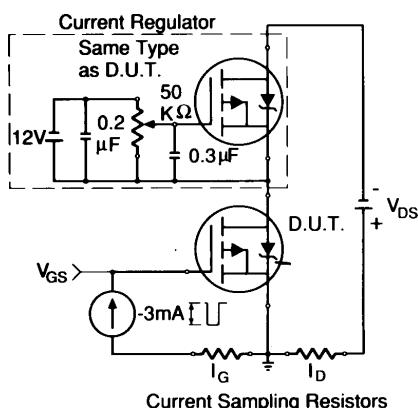


Fig. 13a — Gate Charge Test Circuit

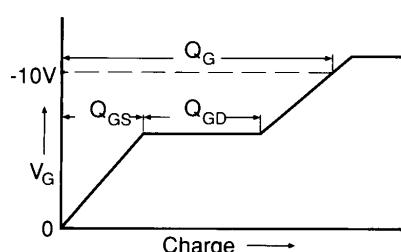
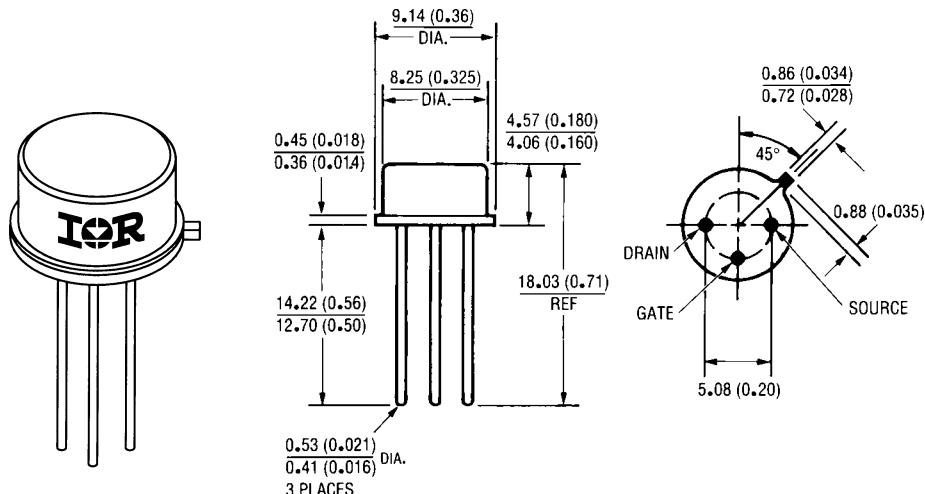


Fig. 13b — Basic Gate Charge Waveform

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- ① Repetitive Rating; Pulse width limited by maximum junction temperature.
(see figure 11)
- ② @ V_{DD} = -25V, Starting T_J = 25°C,
EAS = [0.5 * L * (I_L²) * [BV_{DSS}/(BV_{DSS}-V_{DD})]]
Peak I_L = -4.0A, V_{GS} = -10V, 25 ≤ R_G ≤ 200Ω
- ③ I_{SD} ≤ -4.0A, di/dt ≤ -110A/μs,
V_{DD} ≤ BV_{DSS}, T_J ≤ 150°C
- ④ Pulse width ≤ 300 μs; Duty Cycle ≤ 2%
- ⑤ K/W = °C/W
W/K = W/°C

Case Outline and Dimensions — TO-205AF (Modified TO-39)



All dimensions are shown millimeters (inches)

International
IR Rectifier

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